

REMARKS

Claims 1-11 are pending in this application. By this Amendment, claim 1 is amended. No new matter is added. Reconsideration in view of the above the amendments and following remarks is respectfully requested.

The Office Action rejects claims 1-2 and 8 under 35 U.S.C. §102(e) as being anticipated by Okamoto (U.S. Patent No. 6,897,007); rejects claim 3 under 35 U.S.C. §103(a) as being unpatentable over Okamoto in view of Reichmanis (U.S. Patent No. 4,373,018); and rejects claim 4 under 35 U.S.C. §103(a) as being unpatentable over Okamoto in view of Xu (U.S. Patent No. 6,335,149). Applicants respectfully traverse these rejections.

Okamoto fails to particularly disclose or suggest the second exposure step of performing exposure for the developed photosensitive resin layer at a substrate temperature of 100 to 250°C with an illuminance of 80 mW/cm² or more and an irradiation energy of greater than 10 J/cm² to less than or equal to 30 J/cm², as recited in independent claim 1.

Okamoto relates to a method for forming an image including exposing a photosensitive lithographic printing plate having a photosensitive layer. Okamoto, in the Abstract, discloses image formation is carried out by subjecting the photosensitive layer of the photosensitive lithographic printing plate to scanning exposure with a laser light having a wavelength range of from 650 to 1300 nm, developing the image, and then subjecting the whole surface to post-exposure.

In col. 15, lines 60-64, Okamoto discloses that, after the development treatment, the image formation method carries out the whole image exposure with an exposure energy of 15 to 70 times greater than that of the scanning exposure with the laser light.

Okamoto, at col. 16, lines 29-36, discloses an illuminance range of 15 mW/cm² to 700 mW/cm². At col. 16, lines 9-17, Okamoto discloses that an exposure energy range of

from 10 mJ/cm² to 10 J/cm². However, Okamoto fails to disclose the exposure energy range recited in independent claim 1.

Therefore, Okamoto fails to particularly disclose the second exposure step of performing exposure for the developed photosensitive resin layer at a substrate temperature of 100 to 250°C with an illuminance of 80 mW/cm² or more and the radiation energy of greater than 10 J/cm² to less than or equal to 30 J/cm², as recited in independent claim 1.

In view of the foregoing, Applicants respectfully submit that independent claim 1 defines patentable subject matter. Claims 2-11 depend from independent claim 1, and therefore are patentable for the same reasons, as well as for the additional features recited therein. Thus, Applicants respectfully request that the Examiner withdraw the rejections.

In view of the foregoing, Applicants respectfully submit that this application is in condition for allowance. Favorable reconsideration and prompt allowance of claims 1-11 are earnestly solicited.

Should the Examiner believe that anything further is desirable in order to place this application in even better condition for allowance, the Examiner is invited to contact the undersigned at the telephone number set forth below.

Respectfully submitted,



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